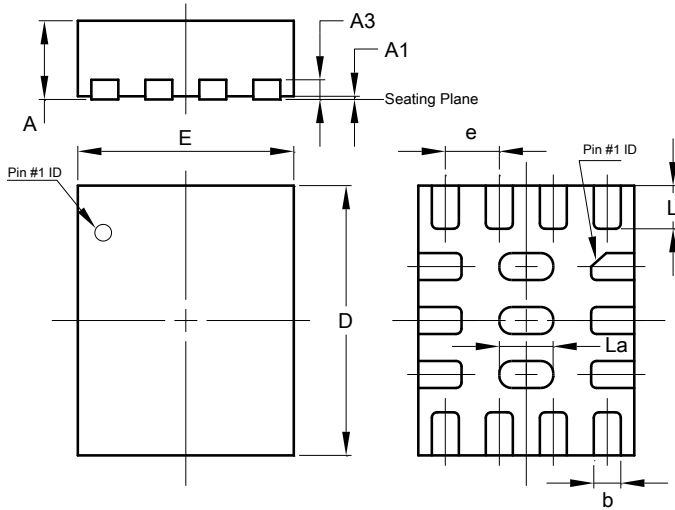


Package Outline Dimensions

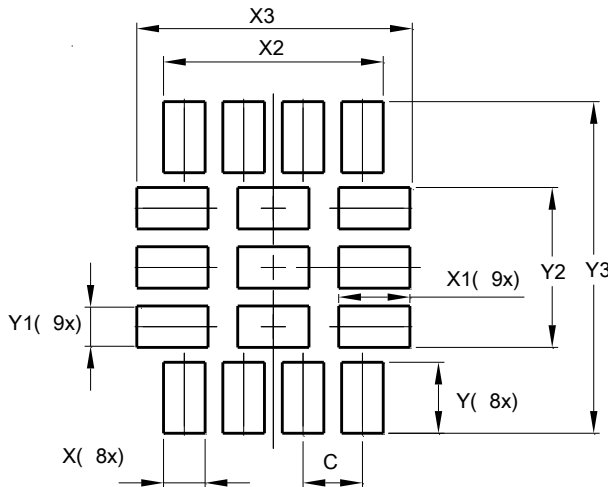
W-FLGA2520-17



W-FLGA2520-17		
Dim	Min	Max
A	0.700	0.800
A1	0	0.050
A3	0.0203REF	
b	0.200	0.300
D	2.420	2.580
E	1.950	2.050
e	0.500TYP	
L	0.320	0.480
La	0.424	0.576
All Dimensions in mm		

Suggested Pad Layout

W-FLGA2520-17



Dimensions	Value (in mm)
C	0.500
X	0.350
X1	0.600
X2	1.850
X3	2.320
Y	0.600
Y1	0.350
Y2	1.350
Y3	2.800

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.